



## Gurmeet Singh

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<https://swiftgurmeet.github.io/resume/>

### Summary

I have over 25 years of leading edge technical experience both as a leader and an individual contributor with a record of highly effective, flawless and prolific execution. My strengths include a vast array of skills and expertise, good communication/analytical skills and ingenuity.

### Experience

#### **[18-PRESENT] CONSULTANT, CONFIDENTIAL**

- Physical design methodology for a 7nm Machine Learning chip. Design of global clock distribution network, spice modeling/simulation and ICC2 implementation.

#### **[16-17] CONSULTANT, ZGLUE INC.**

- Physical design methodology and netlist-to-gds flow development in tcl using Cadence toolset. Also Assura physical verification and logical equivalence (lec) flows.
- Hierarchical implementation of an instance array design including floorplanning, power grid, pin placement, place and route, logical equivalence and physical verification.
- Abstract generation of analog macros and hierarchical instance to allow for through the block routing.
- Mixed-signal custom CAD support including SKILL programming
- Setup Virtuoso QRC extraction flow for full chip STA, set up and run full chip STA with Tempus, set up and run full chip LEC with Conformal. Silicon success.

#### **[15-16] MACHINE LEARNING/SOFTWARE ENGINEER**

- Data Science/Machine Learning/Programming Student - See courses below
- Kaggle Participant (<https://www.kaggle.com/gary347>)
- Swift iOS Programming

#### **[13-14] QUALCOMM TECHNOLOGIES, SENIOR STAFF ENGINEER**

Design of the top level floorplan including power grid with multiple power domains, using CPF/UPF for a mixed signal design, automated floorplan generation with Tcl. Wrote power intent CPF from scratch. Full chip formal (LEC) and low power (CLP) verification using Cadence tools. Apache Redhawk EM/IR debug and fixes. My leadership enabled a rare ahead of schedule tapeout. Received two Qualstars. Silicon success (WCD9335).

**[12-13] CADENCE DESIGN SYSTEMS, STAFF APPLICATION ENGINEER**

- Developed a complete, automated rtl2gds reference flow (14nm/finFET) using Cadence tools for a leading edge foundry to provide to its customers. Proven using the same flow, an implementation of an ARM A9 processor core including neon coprocessor@2.4GHz/Typ.
- Implemented a 28nm DDR-PHY IP for tapeout.

**[11-12] SANDFORCE INC., PRINCIPAL ENGINEER**

- Developed a 40 nm automated and optimized, tapeout ready, Cadence based implementation flow.
- Wrote Tcl scripts for a correct by construction, tunable flow used for all blocks.
- Developed automated, tapeout ready, STA setup using Primetime-SI using Tcl/Perl scripts.
- Implemented several large blocks at tapeout quality using the above flow ; the resulting GDSII were timing, LEC, LVS/DRC clean. Silicon success.
- Helped grow the size and capability of the physical design team and lead technical direction.

**[08-11] CONTRACTOR/ENGINEER @(MULTIPLE)**

- Setup 40nm Cadence based, automated, tapeout ready, block level implementation flow.
- Hierarchical physical implementation flow in 65nm technology using Cadence.
- Telecom ASIC: Implementation of two large blocks using Magma. Silicon Success.
- 65nm WiFi ASIC: Implementation of large block using Magma. Silicon Success.
- 65nm WiFi ASIC: Full chip EM/IR signoff using Apache-Redhawk. Silicon Success.

**[06-08] TERANETICS, PRINCIPAL ENGINEER**

130nm/65nm 10GBASE-T PHY ASIC: Implement many large blocks, some using x-route. Automate implementation, static timing analysis, logical equivalence and physical verification flows. Power estimation; power reduction using special cells. Silicon Success.

**[04-06] AIRGO NETWORKS, PHYSICAL DESIGN MANAGER**

Multiple WiFi ASICs: Implement many blocks using Magma. Automate PTSI STA, formal, Calibre PV flows. Full chip EM/IR signoff using Apache-Redhawk. Tapeout signoff/jobview. ECOs, I/O Spice sims, IP integration, Methodology, Project Management. Silicon success.

**[01-04] TRANSMETA, SENIOR MEMBER, TECHNICAL STAFF**

1.2/1.8GHz Efficeon CPUs: Implement Hypertransport unit with place and route tools; Register File design. ECOs. Setup latch compatible STA flow. Array and noise methodologies. Silicon Success.

**[99-01] SUN MICROSYSTEMS, MEMBER, TECHNICAL STAFF**

- UltraSparc V CPU: Custom circuit design of a content addressable register file and an arrayed random logic block
- 1.2GHz UltraSparc III CPU: Ported a dozen 130nm dynamic circuit blocks, including adders up to 64-bits, from 180nm to 130nm. Wrote a Pathmill API hook in C to automate generation of timing models. Silicon success.

**[97-99] INTEL CORPORATION, DESIGN ENGINEER**

- 833MHz Pentium III Xeon CPU: High speed dynamic circuit design for L2Cache ECC encoder, L2 Cache STA analysis and EM/IR verification. Silicon success.
- 600 MHz Pentium III CPU : GTL I/O circuit design including one invention disclosure. Silicon success.

**[94-97] ST MICROELECTRONICS, DESIGN ENGINEER**

Circuit Design of 32kx8, 128kx8 SRAMs. Silicon success. CAD setup. Reverse engineer a register file and re-implement, verify functionality using verilog switch level simulation. Silicon success.

## Education

I was the best student in my class for all seven years of college level education, including four at India's premium engineering institution.

**[2015-2016]: ONLINE COURSERA COURSES**

- Machine Learning
- Machine Learning With Big Data
- Practical Machine Learning
- R Programming
- Statistical Inference
- Reproducible Research
- Regression Models
- Functional Programming Principles in Scala
- Object Oriented Programming in Java
- Financial Markets
- Graph Analytics for Big Data
- Hadoop Platform and Application Framework
- The Data Scientist's Toolbox
- Getting and Cleaning Data
- Exploratory Data Analysis
- Developing Data Products
- Introduction to Big Data
- Introduction to Big Data Analytics
- HTML, CSS and Javascript for Web Developers

**[12/2006] U.C. BERKELEY EVENING COURSE**

Introduction to Digital Signal Processing Course, UC Berkeley, A Grade

**[1989-93] M.ENG., ELECTRICAL COMM, INDIAN INSTITUTE OF SCIENCE.**

First class with distinction. Alumni medal, Best Student, 1990-93

**[1986-89] B.SC., PHYSICS, DELHI UNIVERSITY.**

First class with distinction, Gold medal, Best Student: 1987/88/89.